



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-11-28
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HDO7*0062BE6	A	BOZA	2018-11-28
	Amount	UoM	Unit type	ST ECOPACK Grade
	80	mg	Each	ECOPACK® 3
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85x3.9x1.52	8	gull wing	
Comment	07 SO 08 .15 JEDEC; MDF valid for TL062IDT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
;				0
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg. will not be declared in this document						Mfr Item Name	HDO7*0062BE6				49999998.0	1000007.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.089	mg	supplier	die	Silicon (Si)	7440-21-3		1.069	mg	981635	13363
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	8264	113
				supplier	Passivation	Silicon Nitride	12033-89-5		0.005	mg	4591	63
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	5510	75
Leadframe	M-004 Copper and its alloys	31.058	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.810	mg	959817	372625
				supplier	alloy	Iron (Fe)	7439-89-6		0.701	mg	22571	8763
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.042	mg	1352	525
				supplier	alloy	Zinc (Zn)	7440-66-6		0.037	mg	1191	463
				supplier	metallization	Nickel (Ni)	7440-02-0		0.429	mg	13813	5363
				supplier	metallization	Palladium (Pd)	7440-05-3		0.027	mg	869	338
Die attach	M-008 Precious metals	0.424	mg	supplier	metallization	Gold (Au)	7440-57-5		0.012	mg	386	150
				supplier	glue	Silver (Ag)	7440-22-4		0.373	mg	879717	4663
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.021	mg	49528	263
Die attach	M-015 Other organic materials	0.424	mg	supplier	glue	Acrylate resin	5888-33-5		0.021	mg	49528	263
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.009	mg	21226	113
				supplier	wire	Copper (Cu)	7440-50-8		0.043	mg	1000000	538
Bonding wires	M-011 Other inorganic materials	0.043	mg	supplier	wire	Copper (Cu)	7440-50-8		0.043	mg	1000000	538
				supplier	mold compound	Silica, vitreous	60676-86-0		41.036	mg	865994	512950
				supplier	mold compound	Epoxy Resin	Proprietary		3.554	mg	75001	44425
				supplier	mold compound	Phenol Resin	Proprietary		2.369	mg	49994	29613
Encapsulation	M-015 Other organic materials	47.386	mg	supplier	mold compound	Carbon black	1333-86-4		0.237	mg	5001	2963
				supplier	mold compound	Bismuth compound	7440-69-9		0.190	mg	4010	2375
				supplier	mold compound							